

# SOT1444-4

wafer level chip-scale package; 49 bumps; 2.98 x 3.43 x 0.56 mm (Backside coating included)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP49
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	21-7-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.4	-	3.43	3.46	mm
E	package width	2.95	-	2.98	3.01	mm
A	seated height	0.52	-	0.56	0.6	mm
A <sub>2</sub>	package height	0.335	-	0.36	0.385	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	49	-	



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2. Package outline

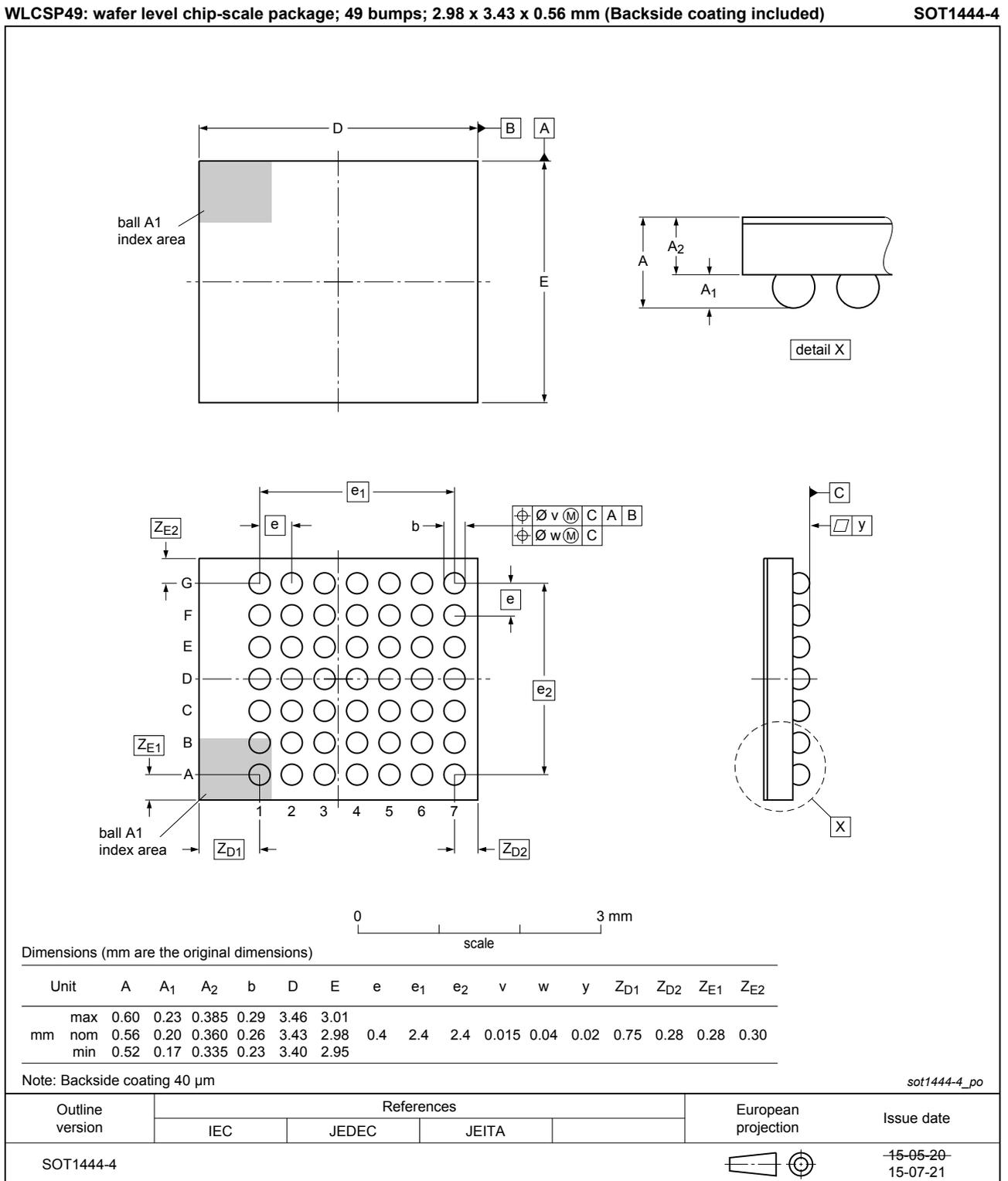


Fig. 1. Package outline WLCSP49 (SOT1444-4)

wafer level chip-scale package; 49 bumps; 2.98 x  
3.43 x 0.56 mm (Backside coating included)

### 3. Legal information

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